

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Patent Application of:
Cyprian Emeka Uzoh et al.

Reissue Application No.: Not Yet Known
(U.S. Patent 6,297,140)

Group Art Unit: Not Yet Known

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Examiner: Not Yet Known

PRELIMINARY AMENDMENT

MS REISSUE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please amend the application as discussed below.

In The Claims:

Please amend the claims as follows:

1.(Amended) A method for plating a second metal directly to a first metal, said method comprising [the steps of]:

providing a semiconductor substrate including at least one metal feature and at least one insulating layer covering said metal feature and said substrate;

forming at least one recess in said at least one insulating layer thereby exposing at least a portion of said metal feature;

forming at least one conductive barrier layer over said insulating layer and said exposed portion of said metal feature;

forming a plating seed layer of a first metal over said at least one barrier layer;

depositing a photoresist layer over aid plating seed layer;